



US 20240224426A1

(19) **United States**

(12) **Patent Application Publication**
UMEMURA et al.

(10) **Pub. No.: US 2024/0224426 A1**

(43) **Pub. Date: Jul. 4, 2024**

(54) **WIRING SUBSTRATE**

Publication Classification

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(51) **Int. Cl.**

H05K 1/16 (2006.01)

H05K 1/03 (2006.01)

H05K 1/11 (2006.01)

(52) **U.S. Cl.**

CPC **H05K 1/162** (2013.01); **H05K 1/0306** (2013.01); **H05K 1/115** (2013.01); **H05K 2201/068** (2013.01); **H05K 2201/09536** (2013.01); **H05K 2201/0959** (2013.01); **H05K 2201/09827** (2013.01)

(21) Appl. No.: **18/604,992**

(22) Filed: **Mar. 14, 2024**

Related U.S. Application Data

(63) Continuation of application No. PCT/JP2022/028287, filed on Jul. 21, 2022.

Foreign Application Priority Data

Sep. 15, 2021 (JP) 2021-150441

(57)

ABSTRACT

A component (capacitor) of the high-frequency circuit provided on a first surface of the glass substrate, and the bottom of the through hole in the glass substrate on the first surface have an overlapping part on the first surface. As a result, the capacitor is formed directly above the via, that is, the through hole, thereby eliminating the need for conductive wiring from the via to the capacitor. In addition, by forming a capacitor on a very flat glass substrate before forming the through hole, and forming the through hole after that, it is possible to stably form the capacitor.

